



IPW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:  
Cheung, et al.  
  
Serial No.: 10/686,486  
  
Filed: October 15, 2003  
  
For: Apparatus for Electro  
Chemical Deposition of  
Copper Metallization With  
The Capability of In-situ  
Thermal Annealing

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Group Art Unit: 1753

Examiner:

MAIL STOP  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

CERTIFICATE OF MAILING  
37 CFR 1.8

I hereby certify that this correspondence is being deposited on  
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November 9, 2005  
Date

  
Signature

Dear Sir:

STATUS INQUIRY

More than 24 months have passed since

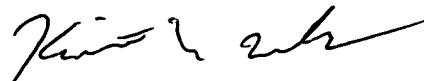
☒ the filing of this application on October 15, 2003.

☐ the filing of . response on .

No communication has been received from the Patent and Trademark Office  
indicating action on this application or response.

Kindly advise the undersigned of the present status of this application. A  
stamped return-addressed envelope is provided.

Respectfully submitted,



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